

SDRAM DDR3 512MX8 ½ Density Device Technical Note

Introduction

This technical note provides an overview of how the SGG256M8V00HK8DA-12K DDR3 SDRAM device is configured and tested as a 2Gb device.

This device is internally configured as a standard 2Gb 256MX8 JEDEC standard device.

Addressing

Parameter	4Gb ½ Density Device Configuration 2Gb 256M X8	4Gb Device Configuration for reference only 4Gb 512M X 8
Configuration	32MEG X 8 X 8 Banks	64MEG X 8 X 8 Banks
Refresh count	8K	8K
Row addressing	32K A0-A14	64K A0-A15
Bank addressing	8: BA0-BA2	8: BAO-BA2
Column addressing	1K A0-A9	1K A0-A9
Page Size	1KB	1KB

Spectek Component Part Options and Designations

Options	Designation
Spectek Memory	SGG Spectek Component sales
Component depth	256MEG
Component width	x8
Design ID	V00H (1/2 density device)
Operating voltage	1.35V
Refresh	8: 8K
Component package type:	DA: 78b 8X10.5MM
Material type	RoHS - LEAD-FREE
Device speed	-12K 1600MHz 11-11-11-1.35V















































































Pin Descriptions

Symbol	Type	Description
A0-A14	Input	Address inputs: Provide the row address for ACTIVE commands, and the column address and auto precharge bit (A10) for READ/WRITE commands, to select one location out of memory array in the respective bank. A10 sampled during a PRECHARGE command determines whether the PRECHARGE applies to one bank (A10 LOW, bank selected by BA[2:0]) or all banks (A10 HIGH). The address inputs also provide the op-code during a LOAD MODE command. Address inputs are referenced to Vrefca. A12: When enable in the mode register (MR), A12 is sampled during READ and WRITE commands to determine whether burst chop (on-the-fly) will be performed (HIGH = BL8 or no burst chop, LOW = BC4)
BA0-BA2	Input	Bank address inputs: Define the device bank to which an ACTIVE, READ, WRITE, or PRECHARGE command is being applied. BA[2:0] define which mode register (MR0, MR1, MR2 or MR3) is loaded during the LOAD MODE command. BA[2:0] are reference to Vrefca
CKx CKx#	Input	Clock: Differential clock inputs. All control command and address input signals are sampled on the crossing of the positive edge of CK and the negative edge of CK#. Output data strobe (DQS, DSS#) is referenced to crossings of CK and CK#.
CKE	Input	Clock enable: Enables (registered HIGH) and disables (registered LOW) internal circuitry and clocks on the DRAM.
CS#	Input	Chip select: CS# enables (registered LOW) and disables (registered HIGH) the command decoder. All commands are masked when CS# is registered HIGH. CS# provides for external bank selection on systems with multiple ranks. CS# is considered part of the command code.
DM	Input	Data mask (x8 devices only): DM is an input mask signal for write data. Input data is masked when DM is sampled HIGH, along with the input data during a write access. Although DM pins are input-only, DM loading is designed to match that of the DQ and DQS pins.
ODT	Input	On-die termination: Enables (registered HIGH) and disables (register LOW) termination resistance internal to the DDR3 SDRAM. When enabled in normal operation, ODT is only applied to the following pins: DQ, DQS, DQS#, DM and CB. The ODT input will be ignored if disabled via the LOAD MODE command.
RAS#, CAS#, WE#	Input	Command inputs: RAS#, CAS# and WE# (along with CS#) define the command being entered.
RESET#	Input	Reset: RESET# is an active LOW CMOS input referenced to Vss. The RESET# input receiver is a CMOS input defined as a rail-to rail signal with DC HIGH $\geq 0.8 \times V_{dd}$ and DC LOW $\leq 0.2 \times V_{dd}$. RESET# assertion and deseerion are asynchronous.
DQ0- DQ7	I/O	Data input/output: Bidirectional data bus.
DQS DQS#	I/O	Data strobe: Differential data strobes. Output with read data: edge-aligned with read data: input with read data: input with write data: center-aligned with write data

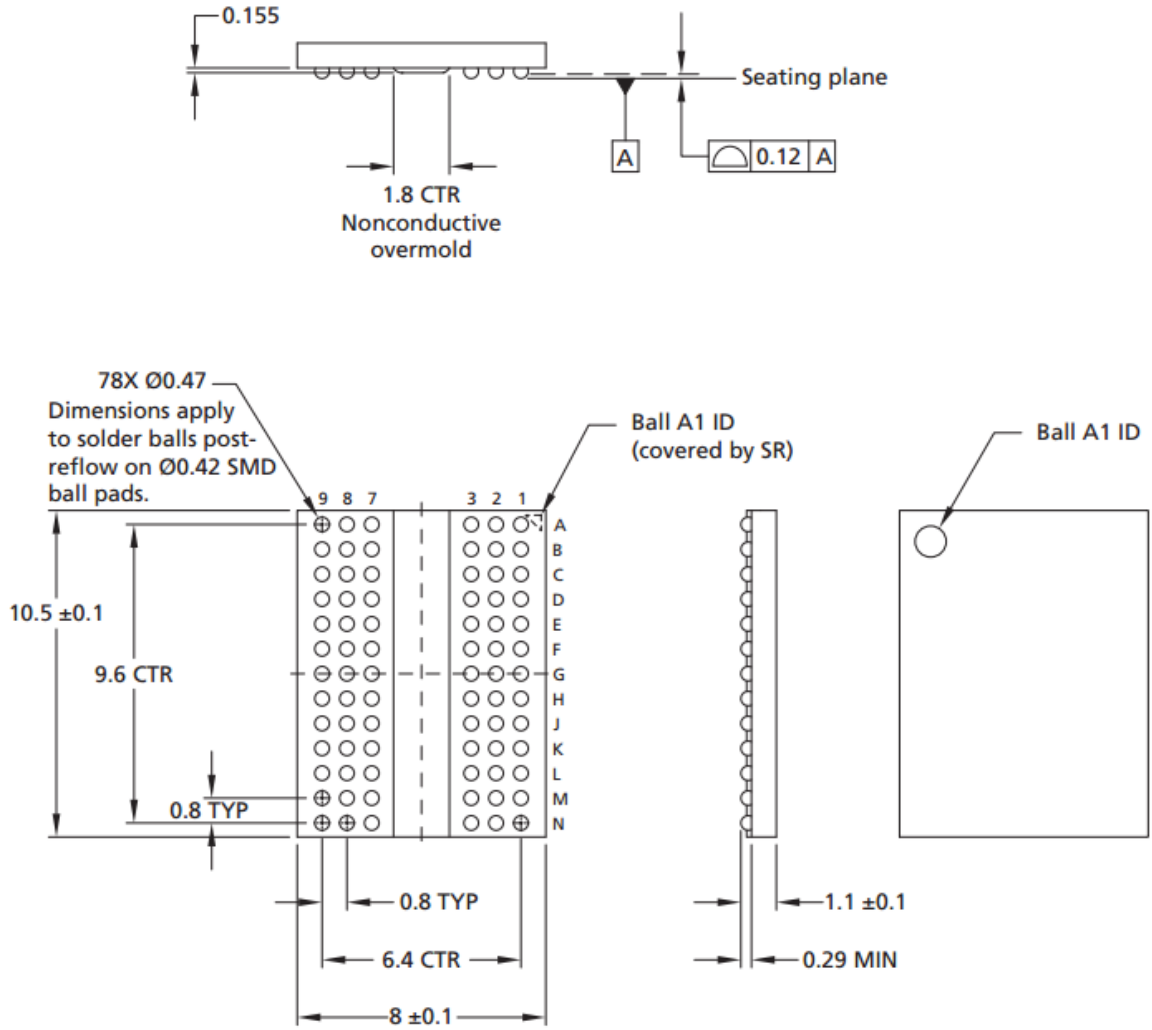
Pin Descriptions - Continued)

Symbol	Type	Description
TDQS TDQSx#	Output	Termination data strobe (x8 devices only) When TDQS is enabled, DM is disabled and TDQS and TDQS# provide termination resistance.
Vdd	Supply	Power Supply: 1.5V \pm 0.1V.
VddQ	Supply	DQ Power Supply: 1.5V \pm 0.1V Isolated on the device for improved noise immunity.
Vddrefca	Supply	Reference voltage for control, command and address: Vrefca must be maintained at all times (including self refresh) for proper device operation.
Vrefdq	Supply	Reference voltage for data: Vrefdq must be maintained at all times (excluding self refresh) for proper device operation.
Vss	Supply	Ground
VssQ	Supply	DQ ground: Isolated on the device for improved noise immunity.
ZQ	Reference	External reference ball for output drive calibration: This ball is tied to an external 240 ohm resistor (RZQ) which is tied to Vssq.
NC	-	No connect: These balls should be left unconnected (the ball has no connection to the DRAM or to other balls)
NF	-	No function: When configured as X4 device, these balls are NF. When configured as X8 device, these balls are defined as TDQS#,DQ[7:4].

Ball Assignments and Descriptions
78 – Ball FBGA X8 (Top View)

	1	2	3	4	5	6	7	8	9
A	 V _{SS}	 V _{DD}	 NC				 NF, NF/TDQS#	 V _{SS}	 V _{DD}
B	 V _{SS}	 V _{SSQ}	 DQ0				 DM, DM/TDQS	 V _{SSQ}	 V _{DDQ}
C	 V _{DDQ}	 DQ2	 DQS				 DQ1	 DQ3	 V _{SSQ}
D	 V _{SSQ}	 NF, DQ6	 DQS#				 V _{DD}	 V _{SS}	 V _{SSQ}
E	 V _{REFDQ}	 V _{DDQ}	 NF, DQ4				 NF, DQ7	 NF, DQ5	 V _{DDQ}
F	 NC	 V _{SS}	 RAS#				 CK	 V _{SS}	 NC
G	 ODT	 V _{DD}	 CAS#				 CK#	 V _{DD}	 CKE
H	 NC	 CS#	 WE#				 A10/AP	 ZQ	 NC
J	 V _{SS}	 BA0	 BA2				 NC	 V _{REFCA}	 V _{SS}
K	 V _{DD}	 A3	 A0				 A12/BC#	 BA1	 V _{DD}
L	 V _{SS}	 A5	 A2				 A1	 A4	 V _{SS}
M	 V _{DD}	 A7	 A9				 A11	 A6	 V _{DD}
N	 V _{SS}	 RESET#	 A13				 A14	 A8	 V _{SS}

78 – Ball FBGA Package 8 X 10.5MM (DA, x8, Package)



- Notes: 1. All dimensions are in millimeters.
 2. Solder ball material: SAC302 (96.8% Sn, 3% Ag, 0.2% Cu).